CLAIMS

1. A method for manufacturing a hollow package, the method comprising the following steps 1 and 2:

(step 1) providing one or more closed hollow parts by forming a partition wall and a top plate that are comprised of at least one organic material on a substrate; and

(step 2) compression-molding a sealing resin composition at a low pressure of 0.1 MPa or more and less than 5.0 MPa to resin-seal the substrate, the partition wall, and the top plate,

wherein the step 1 includes a step of mounting one or more elements selected from the group consisting of a semiconductor element, a MEMS component, and an electronic component on the substrate so that the one or more elements are disposed in the one or more closed hollow parts, and

the sealing resin composition contains:

(A) an epoxy resin containing one or more epoxy resins selected from the group consisting of an epoxy resin containing two epoxy groups in a molecule and an epoxy resin containing three or more epoxy groups in a molecule; and

(B) an inorganic filler.

2. The method for manufacturing a hollow package according to claim 1, wherein the organic material is a photosensitive dry film resist.

3. The method for manufacturing a hollow package according to claim 2, wherein the organic material is a negative photosensitive dry film resist.

4. The method for manufacturing a hollow package according to claim 3, wherein the organic material is the negative photosensitive dry film resist containing a photoacid generator and an epoxy resin.

5. The method for manufacturing a hollow package according to claim 1, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a

triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

6. The method for manufacturing a hollow package according to claim 2, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

7. The method for manufacturing a hollow package according to claim 3, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

8. The method for manufacturing a hollow package according to claim 4, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

9. A method for manufacturing a hollow package, the method comprising: forming a partition wall and a top plate that are comprised of at least one organic material on a substrate, thereby providing an assembly of the substrate, the partition wall, and the top plate, the assembly having one or more closed hollow parts and compression-molding a sealing resin composition surrounding the assembly of the substrate, the partition wall, and the top plate at a low pressure of 0.1 MPa or more and less than 5.0 MPa to resin-seal the assembly of the substrate, the partition wall, and the top plate,

wherein one or more elements selected from the group consisting of a semiconductor element, a MEMS component, and an electronic component are mounted on the substrate so that the one or more elements are disposed in the one or more closed hollow parts, and

the sealing resin composition contains:

(A) an epoxy resin containing one or more epoxy resins selected

from the group consisting of an epoxy resin containing two epoxy groups in a molecule and an epoxy resin containing three or more epoxy groups in a molecule; and

(B) an inorganic filler.

10. The method for manufacturing a hollow package according to claim 9, wherein the organic material is a photosensitive dry film resist.

11. The method for manufacturing a hollow package according to claim 10, wherein the organic material is a negative photosensitive dry film resist.

12. The method for manufacturing a hollow package according to claim 11, wherein the organic material is the negative photosensitive dry film resist containing a photoacid generator and an epoxy resin.

13. The method for manufacturing a hollow package according to claim 10, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

14. The method for manufacturing a hollow package according to claim 11, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.

15. The method for manufacturing a hollow package according to claim 12, wherein the component (A) contains one or more epoxy resins selected from the group consisting of a biphenyl aralkyl type epoxy resin, a triphenylmethane type epoxy resin, a biphenyl type epoxy resin, and a bisphenol type epoxy resin.